Plastic Packages for Integrated Circuits

Package Outline Drawing
W4x5.20H
20 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm PITCH)
Rev 0, 05/14

Dimension is measured at the maximum bump diameter parallel to primary datum Z.
Primary datum Z and seating plane are defined by the spherical crowns of the bump.
Bump position designation per JESD 95-1, SPP-010.
There shall be a minimum clearance of 0.10mm between the edge of the bump and the body edge.